

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Certificate

APR 04 2006

of Correction

In re Application of:
Thomas S. Roche et al.

Application No.: 10/649,426

Filed: August 26, 2003

) Patent No.: 6,924,172 B2
)
) Issue Date: August 2, 2005
)
) Docket No.: SC1251ZP
)

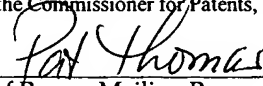
Title: METHOD OF FORMING A BOND PAD INCLUDING REMOVING A PORTION
OF A PROTECTIVE LAYER

Certificate of Mailing

Date of deposit:

3-27-06

I hereby certify that this paper is being deposited with the United States Postal Service on the date indicated above, as first-class mail, with sufficient postage attached thereto, in an envelope addressed to the Commissioner for Patents, Alexandria, VA 22313.


Signature of Person Mailing Paper

Pat Thomas
Printed Name of Person Mailing Paper

Certificate of Corrections Branch
Commissioner for Patents
Alexandria, VA 22313

SUBMISSION OF CERTIFICATE OF CORRECTION

Dear Commissioner:

Enclosed, in duplicate, is a Certificate of Correction for error in the subject patent. The amendment to the title of the invention, made at the examiner's request, is not included. Please enter this correction.

Since the error is on the part of the United States Patent Office, there should be no charge.

Respectfully submitted,



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Date

March 26, 2006

APR 14 2006

**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**Page 1 of 1

PATENT NO.: 6,924,172 B2
APPLICATION NO: 10/649,426
DATE: August 2, 2005
INVENTOR(S): Thomas S. Roche et al.

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

On First Page, Title of Invention (Item 54), change:

"METHOD OF FORMING A BOND PAD"

to

-- METHOD OF FORMING A BOND PAD INCLUDING REMOVING A PORTION OF A
PROTECTIVE LAYER--

MAILING ADDRESS OF SENDER (Please do not use customer number below)

Freescale Semiconductor, Inc.
Law Department
7700 West Parmer Lane PL02
Austin, TX 78729

APR -4 2006

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CERTIFICATE OF CORRECTIONPage 1 of 1

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